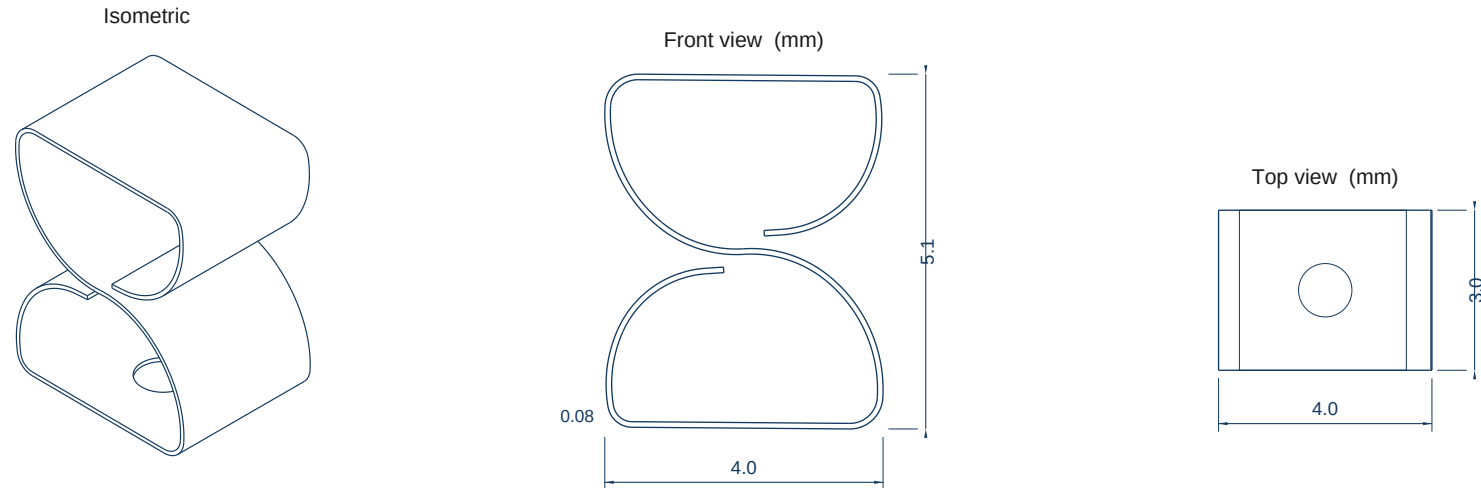




Type 8-03 B803-30040051

SMD EMI Spring Contact | Beryllium Copper | Units: mm



MECHANICAL

VALUE

Thickness	0.08 mm
Width	3.0 mm +/- 0.2
Length	4.0 mm +/- 0.2
Height	5.1 mm +/- 0.2
Form	figure-8: two D-lobes crossing at a waist, 180 deg rotationally symmetric
Base / top land	3.13 mm flat, one land per lobe
Land corners	R0.312 CL 80 deg / R0.433 CL 87 deg
Lobe arcs	flank R1.45/62, R1.88/34 waist R2.06/54, R1.73/43 (CL, deg)
Free tongue	0.25 mm, one per lobe, 0.188 mm clear of the opposite strip
Base hole	dia 1.00 mm at 2.00 / 1.50 mm (centred)
Developed length	20.81 mm
Material / plating	BeCu, Gold-plated (G) or Tin-plated (S)
Volume / mass	4.931 mm ³ 41.2 mg (BeCu)

PRODUCT DATA

VALUE

Mfr P/N	B803-30040051G-SY (Au) / B803-30040051S-SY (Sn)
Brand	Seyunda
Description	SMD EMI Contact 4.0x3.0x5.1mm Au
Packaging	Tape & Reel (TR)
Category	Connectors, Interconnects
Sub-category	Contacts, Spring Loaded (Pogo Pins), and Pressure
Lifecycle / origin	Active / Taiwan, Republic of China
RoHS / REACH	RoHS3 Compliant / REACH Unaffected
ECCN / ESD	EAR99 / Static sensitive: Yes
Datasheet	seyunda.com/datasheet/Seyunda-SMD-Spring-Contacts-Datasheet.pdf
Product page	seyunda.com/type-8-03.html
File format	STEP AP214